

# Tianxiang Wu

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/10058512/publications.pdf>

Version: 2024-02-01

4

papers

8

citations

2682572

2

h-index

2917675

2

g-index

4

all docs

4

docs citations

4

times ranked

1

citing authors

#	ARTICLE	IF	CITATIONS
1	Research on Flip-Chip Bonding Process and Thermal Cycle Reliability Simulation of 3-D Stacked Structure. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 51-58.	2.5	6
2	Electromechanical Performance of Microprobe Test With Cuboid Magnetorheological Damper in Microelectronic Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 723-730.	2.5	0
3	Numerical Investigation on Granular Flow from a Wedge-Shaped Feed Hopper Using the Discrete Element Method. Chemical Engineering and Technology, 2018, 41, 913-920.	1.5	2
4	Research on the Mechanical Properties of Magnetorheological Damping and the Performance of Microprobe Test Process. Journal of Electronic Testing: Theory and Applications (JETTA), 0, , 1.	1.2	0